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**Certificate of Facsimile Transmission**

I hereby certify that the attached Transmittal (2 pages) and Response to the Final Office Action dated November 23, 2005 (7 pages), are submitted to the U.S. Patent and Trademark Office via facsimile number (571) 273-8300 on the date shown below. (Total 9 pages).



Li Mei Vermilya

Date: February 22, 2006,

**RESPONSE UNDER 37 CFR 1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP 2822**

**PATENT APPLICATION  
Docket No.: 9903-071  
Client Ref. No.: S02US035**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Jin-Hyuk LEE, et al.

Serial No.:	10/690,782	Examiner:	Graybill, David E.
Filed:	October 21, 2003	Group Art Unit:	2822
Confirmation No.:	5611		
For:	METHOD FOR MANUFACTURING A WAFER LEVEL CHIP SCALE PACKAGE		

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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Responsive to the Final Office Action November 23, 2005, enclosed is an amendment in the above-identified application.

The fee has been calculated as shown below.

<b><u>CLAIMS AS AMENDED</u></b>					
For:	Number After Amendment	Previous Number	Extra	Rate	Additional Fee
Total Claims	17	19	0	x \$50 =	\$0
Independent Claims	4	4	0	x \$200 =	\$0
<b>TOTAL ADDITIONAL FEE FOR THIS AMENDMENT</b>					<b>\$0</b>

\*greater of twenty (20) or number for which fee has been paid  
\*\*greater of three (3) or number for which fee has been paid

- Any deficiency or overpayment should be charged or credited to deposit account number 13-1703.

**Customer No. 20575**

Respectfully submitted,

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**AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR 1.116**

Responsive to the Final Office Action, Paper No. 20051119, dated November 23, 2005, please amend the application as follows.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.